© Cop	erial Composition yright 2005. IPC, Ban ational and Pan-Ameri	nockburn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, th	ent is a declar he declaratior	ation of th	e substances asses all lowe	within the er level mat	manufactur erials for wl	er listed ite hich the m	em. Note anufactu	e: if the item is an a rer has engineerin	assembly with lowe g responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Information															
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2024-05-10				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Repre	Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Nu	Requester Item Number Mfr Item NV25M0		Number Mfr Item Name 01DWUTG 1MB SPI SER CMOS EEPROM			Effective Date Version Manufacturing Site 2024-05-10 PH1		ing Site	V	Veight*	UOM	Unit Type			
									77.46 mg		Each				
Manufacturing Procces	ss Information					1									
Terminal Plating / C	Terminal Plating / Grid Array Material		erminal Base Alloy J-ST		L Rating	Peak Pro	k Process Body Temperature Max Time at Pea		me at Peak	x Temperature Number of Reflow C		ycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		no CU Alloy	CU Alloy 1			260		С	30		seconds 3				
Comments															
evel 1 - maximum time at pe	ak temperature duri	ing soldering is 10-3	0 seconds												
or more information regard	ling material compos	sition please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.65	mg	Supplier	Silicon (Si)	7440-21-3		2.65	mg
Die Attach	0.21	mg	Supplier	Silver (Ag)	7440-22-4		0.1575	mg
			Supplier	Epoxy resins	129915-35-1		0.0525	mg
Lead Frame	27.35	mg	Supplier	Zinc (Zn)	7440-66-6		0.0274	mg
			Supplier	Iron (Fe)	7439-89-6		0.6291	mg
			Supplier	Copper (Cu)	7440-50-8		26.6663	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0274	mg
Mold Compound-Black	46.76	mg		Epoxy resin	proprietary data		2.338	mg
			Supplier	Phenolic Resin	Proprietary Data		2.338	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.9352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2338	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.915	mg
Plating	0.34	mg	Supplier	Palladium (Pd)	7440-05-3		0.0211	mg
			В	Nickel (Ni)	7440-02-0		0.3152	mg
			Supplier	Gold (Au)	7440-57-5		0.0036	mg
Vire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg